

MECHANICAL CASE OUTLINE

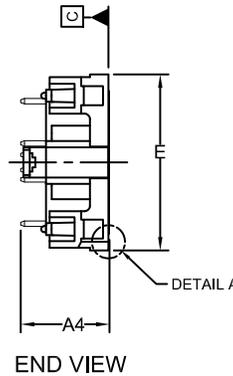
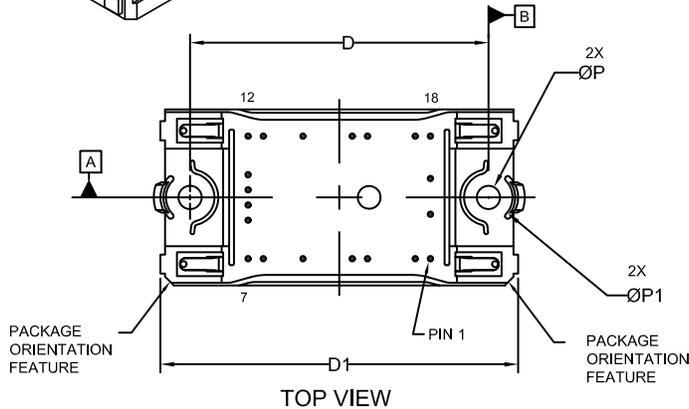
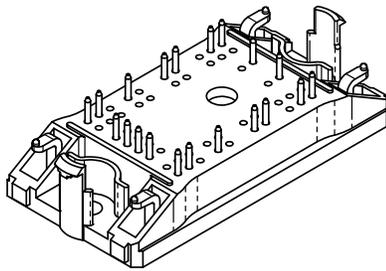
PACKAGE DIMENSIONS

ON Semiconductor®

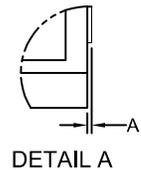
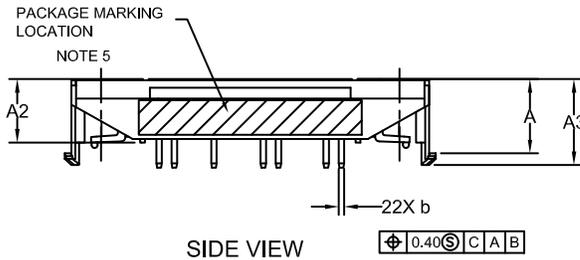


PIM20, 55x32.5 / Q0PACK
CASE 180AB
ISSUE D

DATE 21 NOV 2017



DIM	MILLIMETERS	
	MIN.	NOM.
A	13.50	13.90
A1	0.10	0.30
A2	11.50	11.90
A3	15.65	16.05
A4	16.35 REF	
b	0.95	1.05
D	54.80	55.20
D1	65.60	66.20
E	32.20	32.80
P	4.20	4.40
P1	8.90	9.10



NOTE 4

PIN	PIN POSITION		PIN	PIN POSITION	
	X	Y		X	Y
1	16.80	-11.30	11	-16.80	4.20
2	14.00	-11.30	12	-16.80	11.30
3	5.20	-11.30	13	-14.00	11.30
4	2.40	-11.30	14	-6.70	11.30
5	-6.70	-11.30	15	2.40	11.30
6	-14.00	-11.30	16	5.20	11.30
7	-16.80	-11.30	17	14.00	11.30
8	-16.80	-4.20	18	16.80	11.30
9	-16.80	-1.40	19	16.80	3.50
10	-16.80	1.40	20	16.80	-3.10

NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
- CONTROLLING DIMENSION: MILLIMETERS
- DIMENSION b APPLIES TO THE PLATED TERMINALS AND IS MEASURED BETWEEN 1.00 AND 3.00 FROM THE TERMINAL TIP.
- POSITION OF THE CENTER OF THE TERMINALS IS DETERMINED FROM DATUM B THE CENTER OF DIMENSION D, X DIRECTION, AND FROM DATUM A, Y DIRECTION. POSITIONAL TOLERANCE, AS NOTED IN DRAWING, APPLIES TO EACH TERMINAL IN BOTH DIRECTIONS.
- PACKAGE MARKING IS LOCATED AS SHOWN ON THE SIDE OPPOSITE THE PACKAGE ORIENTATION FEATURES.

MOUNTING FOOTPRINT & MARKING DIAGRAM ON PAGE 2

DOCUMENT NUMBER:	98AON98424F	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	PIM20 55X32.5 / Q0PACK (SOLDER PIN)	PAGE 1 OF 3

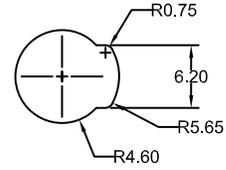
PIM20, 55x32.5 / Q0PACK
CASE 180AB
ISSUE D

DATE 21 NOV 2017

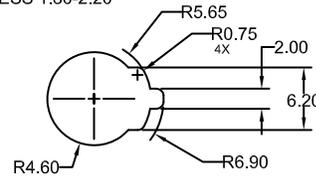
MOUNTING HOLE POSITION

PIN	PIN POSITION		PIN	PIN POSITION	
	X	Y		X	Y
1	16.80	11.30	11	-16.80	-4.20
2	14.00	11.30	12	-16.80	-11.30
3	5.20	11.30	13	-14.00	-11.30
4	2.40	11.30	14	-6.70	-11.30
5	-6.70	11.30	15	2.40	-11.30
6	-14.00	11.30	16	5.20	-11.30
7	-16.80	11.30	17	14.00	-11.30
8	-16.80	4.20	18	16.80	-11.30
9	-16.80	1.40	19	16.80	-3.50
10	-16.80	-1.40	20	16.80	3.10

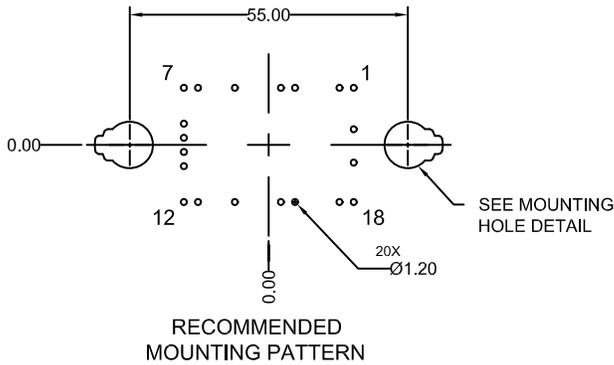
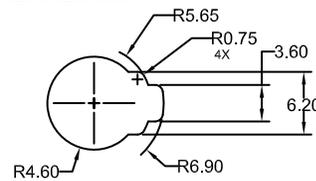
FOR PCB THICKNESS 1.45-1.80



FOR PCB THICKNESS 1.80-2.20

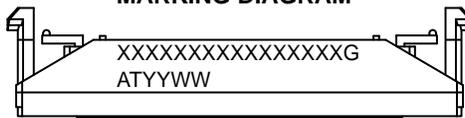


FOR PCB THICKNESS 2.20-2.80



MOUNTING HOLE DETAIL

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code
 G = Pb-Free Package
 AT = Assembly & Test Site Code
 YYWW = Year and Work Week Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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